



Final Product/Process Change Notification

Document #:FPCN23837Z

Issue Date: 27 May 2022

Title of Change:	Wafer fab transfer to onsemi Gresham, Oregon USA from Fab2, Oudenaarde, Belgium related to Fab2 sale. Material change in bondwire type and leadframe.
Proposed Changed Material First Ship Date:	04 Dec 2022 or earlier if approved by customer
Current Material Last Order Date:	22 Aug 2022 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>
Current Material Last Delivery Date:	03 Dec 2022 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>
Product Category:	Active components – Integrated circuits
Contact information:	Contact your local onsemi Sales Office or Nixon.Mathews@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Sample Availability Date:	30 May 2022
PPAP Availability Date:	30 May 2022
Additional Reliability Data:	Contact your local onsemi Sales Office or Catherine.DeKeukeleire@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .
Change Category	
Category	Type of Change
Process - Wafer Production	Change in process technology (e. g. process changes like lithography, etch, oxide deposition, diffusion, die back surface preparation/backgrind, ...), Move of all or part of wafer fab to a different location/site/subcontractor, New / change of passivation or die coating (without bare die), New wafer diameter
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification
Process - Assembly	Change of direct material supplier, Change of lead frame finishing material / area (internal), Change of wire bonding, Change of product marking

Description and Purpose:

	Before Change Description	After Change Description
Change of Orderable Part Number	NCV7707DQR2G NCV7707DQBR2G	NCV7707DQCR2G
Change in process technology	Current: Power Metal Chipbond	New: Cu Power Metal Gresham
Wafer Fab/Wafer Size	Fab2 Substrate: Si (150mm) 6"	Gresham Substrate: Si (200mm) 8"
Change of datasheet parameters/electrical specification	See Datasheet NCV7707/D Rev 7	See Datasheet NCV7707C/D Rev 0
Change of lead frame finishing material / area (internal)	Non Roughened Leadframe	Roughened Leadframe
Change of wire bonding	2mil Au	2mil Cu
Change of product marking	NCV7707 NCV7707B	NCV7707C
Change of Passivation Layer	No Polyimide	Addition of Polyimide
Change in direct Material Supplier	Leadframe Matrial supplier DCI	Leadframe Matrial supplier ASM

Reason / Motivation for Change:

Source/Supply/Capacity Changes Process/Materials Change

Anticipated impact on fit, form, function, reliability, product safety or manufacturability:

The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded.

No anticipated impacts.

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Carmona, Philippines	BelGaN, Oudenaarde, Belgium
onsemi, Gresham United States	

Marking of Parts/ Traceability of Change:

New device marking on the package and new revision ID embedded in the digital.

Reliability Data Summary:

NOTE: AEC -1pager is attached.

To view attachments:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file.



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Electrical Characteristics Summary:

Electrical characteristics will be provided upon request.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
NCV7707DQR2G	NCV7707DQCR2G	NCV7707DQCR2G
NCV7707DQBR2G	NCV7707DQCR2G	NCV7707DQCR2G